

650V 50A SiC Schottky Diode – SiS650S50AS

Rev 1.0 30/10/23

Silicon Carbide Schottky Barrier Rectifier diode in bare die form

Features:

- Capable of high temperature operation >= 175°C
- High Frequency Operation
- High Surge Current Capability
- No Reverse Recovery / No Forward Recovery
- Positive Temperature Coefficient

Ordering Information:

The following part suffixes apply:

- No suffix MIL-STD-750 /2073 Visual Inspection
- "H" MIL-STD-750 /2073 Visual Inspection+ MIL-PRF-38534 Class H LAT
- "K" MIL-STD-750 /2073 Visual Inspection+ MIL-PRF-38534 Class K LAT

LAT = Lot Acceptance Test.

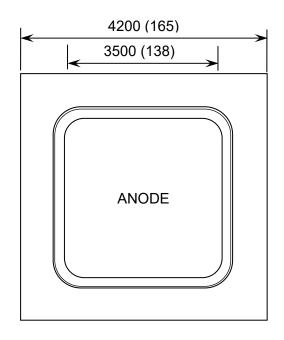
For further information on LAT process flows see below.

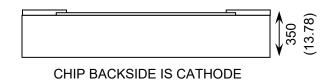
www.siliconsupplies.com\quality\bare-die-lot-qualification

Supply Formats:

- Default Die in Waffle Pack (100 per tray capacity)
- Sawn Wafer on Tape By specific request
- Unsawn Wafer By specific request
- With additional electrical selection By specific request

Die Dimensions in µm (mils)





Mechanical Specification

Die Size (Unsawn)	4200 x 4200 165 x 165	μm mils	
Anode Pad Size	3500 x 3500 138 x 138	μm mils	
Die Thickness	350 (±20) 13.78 (0.79)	μm mils	
Top Metal Composition	Al 4µm		
Back Metal Composition	Ag 0.4µm		





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Absolute Maximum Ratings T_J = 25°C unless otherwise stated

PARAMETER	SYMBOL	VALUE	UNIT
Repetitive peak reverse voltage	V_{RRM}	650	V
Surge peak reverse voltage	V_{RSM}	650	V
DC Peak Blocking Voltage	V_{BR}	650	V
Average forward rectified current	I _{F(AV)}	50	А
Repetitive Peak Forward Surge Current	I _{FRM}	121	A
Peak Single-Cycle Non-Repetitive Surge Current	I _{FSM}	300	А
Operating Junction temperature	T_J	-55 to 175	°C
Storage Temperature Range	T _{STG}	-65 to 175	°C

Electrical Characteristics T_J = 25°C unless otherwise stated

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNIT
Maximum instantaneous forward voltage ¹	V _{F1}	V _{RRM} = 650V, I _{FM} = 50A	-	1.50	1.70	V
	V _{F2}	$V_{RRM} = 650V$, $I_{FM} = 50A$, $T_{J} = 175$ °C	-	2.00	2.40	V
Maximum reverse leakage current ¹	I _{RM} @ V _{RM}	V _R = 650V	-	1	40	μА
	IRM W VRM	V _R = 650V, T _J = 175°C	-	10	60	
Junction Capacitance	Ст	$V_R = 0V$, $f = 1MHz$,	-	3100	-	pF
Reverse Recovery Charge	Q _C	V _R = 400V , I _F = 50A, di/dt = 200A/μs	-	193.4	-	nC
Capacitance Stored Energy	Ec	V _R = 400V	-	47.37	-	μJ

^{1.} Pulse Width≤ 300µs, Duty Cycle ≤ 2.0%

Typical Characteristics T_J = 25°C

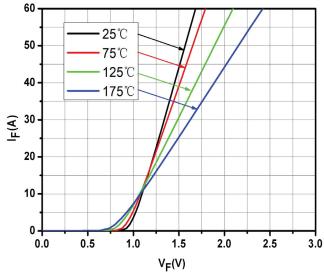


FIGURE 1. Forward Voltage Characteristics

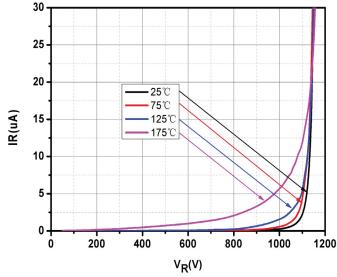


FIGURE 2. Reverse Characteristics

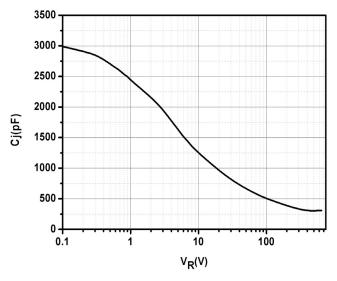




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250 200 150 100 50 0 50 100 150 200 250 300 350 400 450 500 550 600 650 V_R(V)

FIGURE 3. Capacitance Versus Reverse Voltage

FIGURE 4. Total Capacitance Charge Versus Reverse Voltage

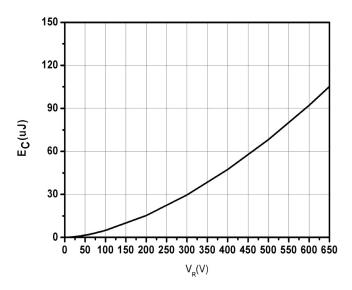


FIGURE 5. Capacitance Stored Energy

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